

600V 10A N-Channel Enhancement Mode Power MOSFET

Description

The AKT10N60T is an N-Channel enhancement mode power MOSFET which using proprietary planar stripe and DMOS technology.

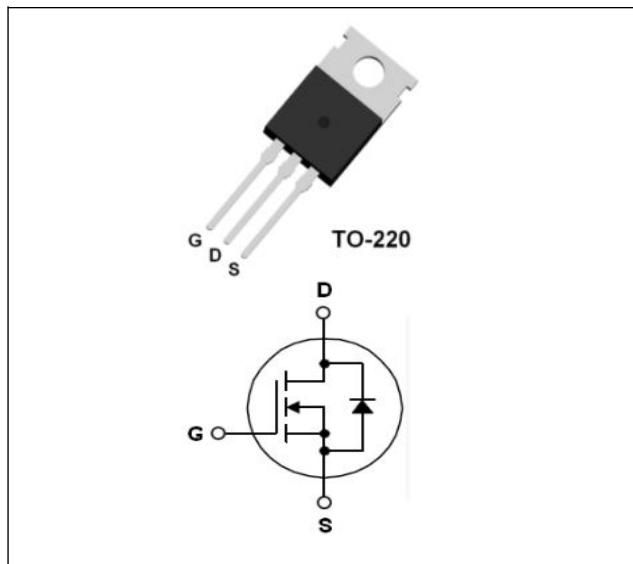
This MOSFET has low static on-resistance and high avalanche energy strength. This device provide excellent switching performance for UPS,DC-DC converters and AC-DC power supply.

Features

- Low on-Resistance: $R_{DS(on)}=0.70\Omega(\text{typ.})$
- Special Process Technology for high ESD Capability
- 100% Avalanche Test
- Good Stability and Uniformity with High E_{AS}

Applications

- UPS Applications
- DC-DC Converters and AC-DC Power Supply



Absolute Maximum Ratings @ $T_C=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter		Ratings	Unit
V_{DSS}	Drain to Source Voltage		600	V
V_{GSS}	Gate to Source Voltage		± 30	V
I_D	Drain Current	$T_C=25^\circ\text{C}$	10	A
		$T_C=100^\circ\text{C}$	6.5	A
I_{DM}	Pulsed Drain Current	(Note1)	40	A
P_D	Maximum Power Dissipation	$T_C=25^\circ\text{C}$	151	W
	Derate above 25°C		1.2	W/ $^\circ\text{C}$
E_{AS}	Single Pulsed Avalanche Energy	(Note 2)	121	mJ
T_J	Operating Junction Temperature Range		-55~+150	$^\circ\text{C}$
T_{STG}	Storage Temperature Range		-55~+150	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	Ratings	Unit
$R_{th(J-C)}$	Thermal Resistance, Junction to case	0.83	$^\circ\text{C}/\text{W}$
$R_{th(J-A)}$	Thermal Resistance, Junction to Ambient	62.5	$^\circ\text{C}/\text{W}$

Electrical Characteristics @ $T_C=25\text{ }^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain to Source Breakdown Voltage	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_D=250\mu\text{A}$	600	-	-	V
$\text{V}_{\text{GS(th)}}$	Gate Threshold Voltage	$\text{V}_{\text{DS}}=\text{V}_{\text{GS}}, \text{I}_D=250\mu\text{A}$	2.0	-	4.0	V
$\text{R}_{\text{DS(on)}}$	Static Drain-Source On-Resistance	$\text{V}_{\text{GS}}=10\text{V}, \text{I}_D=5\text{A}$	-	0.70	0.90	Ω
I_{DSS}	Zero Gate Voltage Drain Current	$\text{V}_{\text{DS}}=600\text{V}, \text{V}_{\text{GS}}=0\text{V}$	-	-	1	μA
I_{GSS}	Gate to Source Leakage Current	$\text{V}_{\text{GS}}=\pm 30\text{V}, \text{V}_{\text{DS}}=0\text{V}$	-	-	± 200	nA

D-S Diode Characteristics and Maximum Rating @ $T_C=25\text{ }^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Maximum Drain to Source Diode Forward Current		-	-	10	A
V_{SD}	Drain-Source Diode Forward Voltage	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_S=10\text{A}$	-	0.88	1.2	V
t_{rr}	Reverse Recovery Time		-	435	-	ns
Q_{rr}	Reverse Recovery Charge	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_S=10\text{A}, \frac{\text{dI}}{\text{dt}}=-100\text{A}/\text{us}$	-	4.1	-	μC

Switching Characteristics @ $T_C=25\text{ }^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$t_{\text{d(on)}}$	Turn-on Delay Time	$\text{I}_D=10\text{A}, \text{V}_{\text{DD}}=300\text{V}, \text{R}_G=25\Omega$ (Note 3)	-	22	-	ns
t_r	Rising Time		-	70	-	ns
$t_{\text{d(off)}}$	Turn-off Delay Time		-	139	-	ns
t_f	Falling Time		-	65	-	ns
C_{iss}	Input Capacitance	$\text{V}_{\text{GS}}=0\text{V}, \text{V}_{\text{DS}}=25\text{V}, f=1.0\text{MHz}$	-	1620	-	pF
C_{oss}	Output Capacitance		-	165	-	pF
C_{rss}	Reverse Transfer Capacitance		-	13	-	pF
Q_g	Total Gate Charge	$\text{I}_D=10\text{A}, \text{V}_{\text{DS}}=480\text{V}$ $\text{V}_{\text{GS}}=10\text{V}$ (Note 3)	-	47	-	nC
Q_{gs}	Gate to Source Charge		-	7.7	-	nC
Q_{gd}	Gate to Drain Charge		-	21.5	-	nC

Note:

1. Repetitive rating: pulse-width limited by maximum junction temperature
2. $L=2\text{mH}, \text{V}_{\text{DD}}=100\text{V}, \text{V}_G=10\text{V}, @T_C=25\text{ }^\circ\text{C}$
3. Essentially independent of operating temperature typical characteristics

Typical Performance Characteristics

Fig. 1. Typical on-Region Characteristics

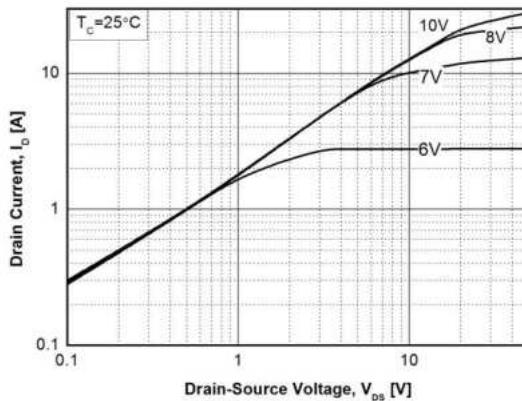


Fig. 3. Static on-Resistance vs. I_D

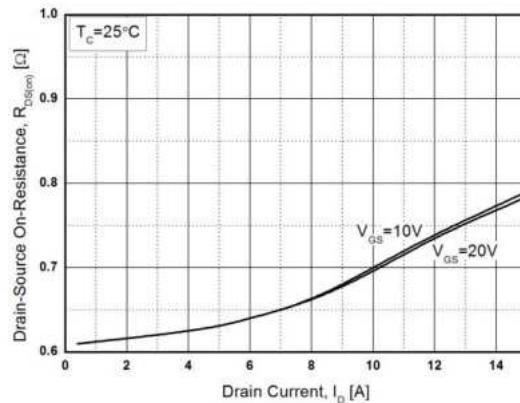


Fig. 5. Capacitance Characteristics

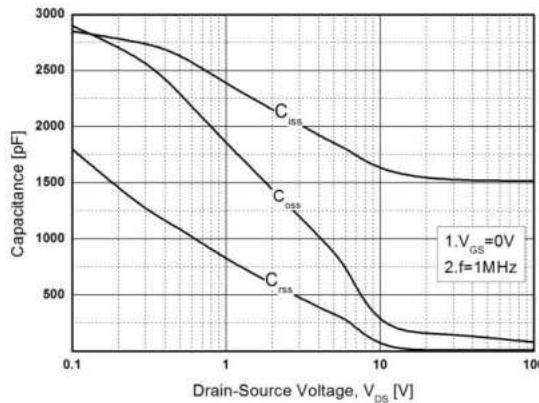


Fig. 2. Typical Transfer Characteristics

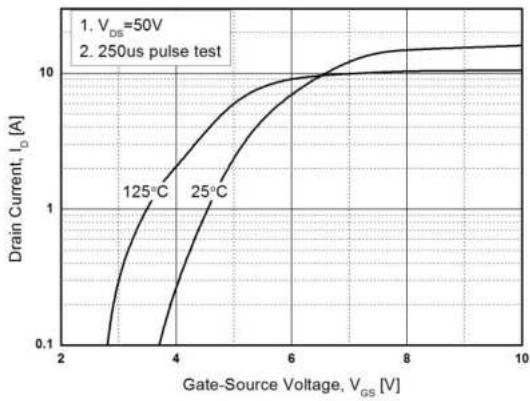


Fig. 4. Body Diode Forward Voltage vs. I_{DR}

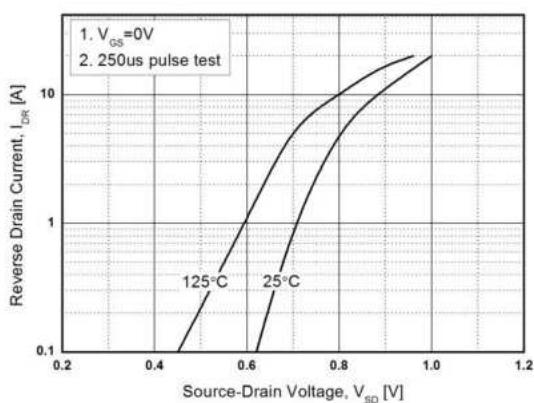
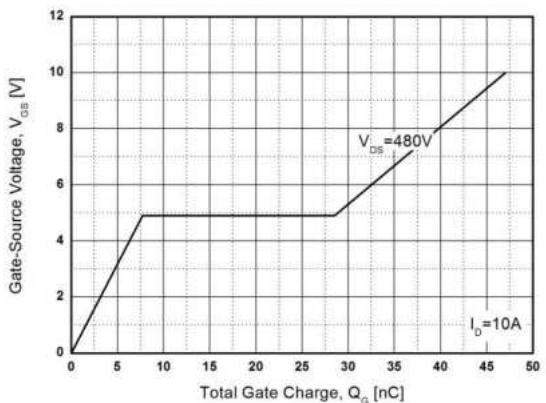


Fig. 6. Gate Charge Characteristics



Typical Performance Characteristics

Fig. 7. Breakdown Voltage vs. Temperature

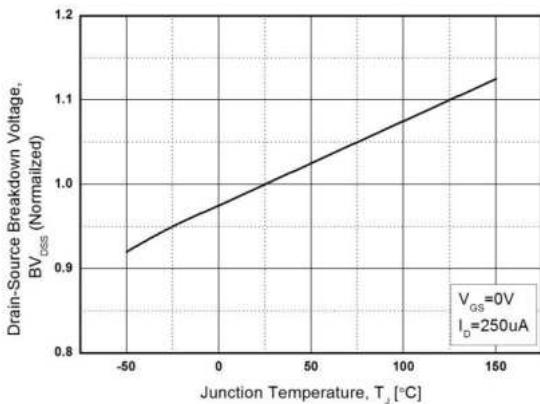


Fig. 8. Static on-Resistance vs. Temperature

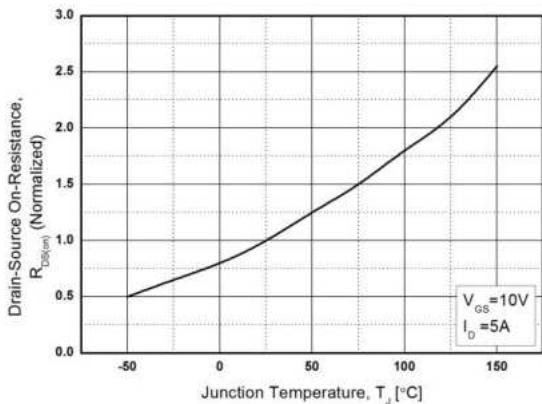


Fig. 9. Maximum Safe Operating Area

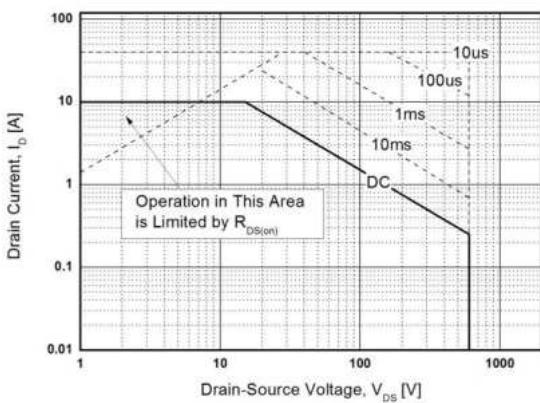


Fig. 10. Maximum Drain Current vs. Temperature

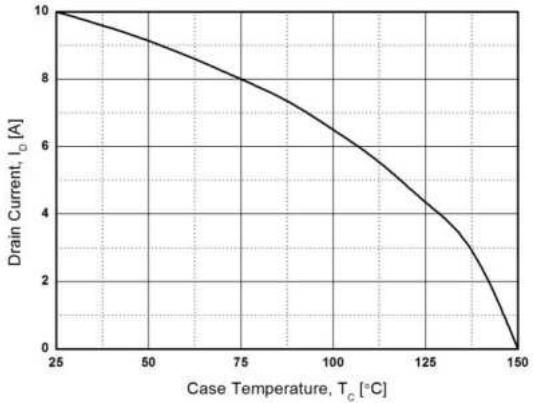
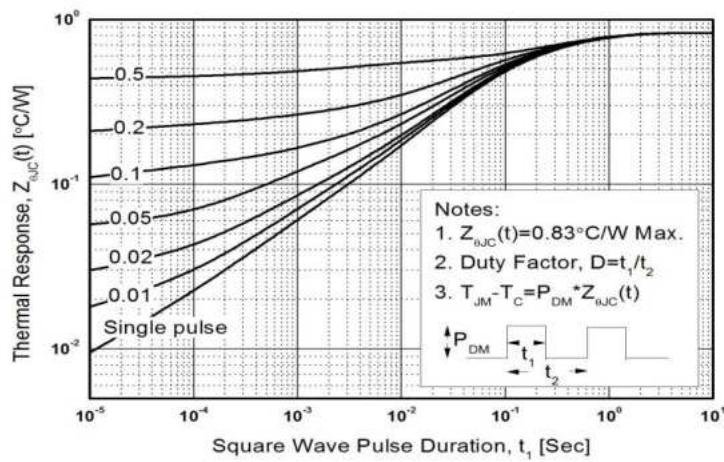


Fig. 11. Transient Thermal Response Curve



Package Dimensions
TO-220

(Dimensions in Millimeters)

